

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Previously Presented) A method of producing a semiconductor device upon receiving an order for the semiconductor device by transferring information between a person who wishes to receive an order and a person who wishes to place an order through a network, the method comprising:

receiving, from a person who wishes to place an order, a plurality of specifications of the semiconductor device;

generating a plurality of circuit patterns based on at least one of the specifications of the semiconductor device, the circuit patterns including a circuit pattern generated by using a stored character projection (CP) aperture for charged-particle beam exposure and a circuit pattern generated by using the stored CP aperture and a CP aperture to be newly produced, and obtaining a plurality of design parameters for each of the circuit patterns, and calculating a cost and a delivery time period for each of the circuit patterns, the cost including a cost for producing the CP aperture to be newly prepared;

presenting said plurality of design parameters with the associated cost and the associated delivery time period for each of the circuit patterns to the person who wishes to place an order for each of the circuit patterns; and

providing the semiconductor device to the person who wishes to place an order when at least one of the plurality of design parameters with the associated cost and the associated delivery time satisfies a desired condition.

2-3. (Cancelled)

4. (Original) The method according to claim 1, further comprising:
requesting a device maker to generate the selected circuit pattern through the network
after the circuit pattern is ordered by the person who wishes to place an order.

5. (Previously Presented) The method according to claim 1, further
comprising: requesting a CP aperture maker to produce the CP aperture to be newly
produced through the network after the circuit pattern is ordered by the person who
wishes to place an order.

6. (Previously Presented) A method of producing a semiconductor
device upon receiving an order for the semiconductor device based on information
transferred between a person who wishes to receive an order and a person who wishes
to place an order through a network, the method comprising:

receiving, from a person who wishes to place an order, a plurality of
specifications of the semiconductor device;

transmitting the specifications of the semiconductor device to a server, and
causing the server to generate a plurality of circuit patterns based on the specifications
of the semiconductor device, the circuit patterns including a circuit pattern generated by
using a stored CP aperture for charged-particle beam exposure and a circuit pattern

generated by using the stored CP aperture and a CP aperture to be newly produced,
and to obtain a plurality of design parameters for each of the circuit patterns;

receiving said plurality of design parameters from the server; and

presenting said plurality of design parameters to the person who wishes to place
an order for each of the circuit patterns and allowing the person who wishes to place an
order to select a circuit pattern satisfying a desired condition.

7-9. (Cancelled)

10. (Previously Presented) A program product for causing a computer
system to produce a semiconductor device upon receiving an order for the
semiconductor device by transferring information between a person who wishes to
receive an order and a person who wishes to place an order through a network, the
program product comprising:

a recording medium; and

first, second, and third instruction means which are operated by the computer
system and are recorded on the recording medium, wherein

the first instruction means provides the computer system with an instruction
allowing the person who wishes to place an order to input specifications of the
semiconductor device by request of the person who wishes to receive an order;

the second instruction means generates a plurality of circuit patterns based on
the specifications of the semiconductor device, the circuit patterns including a circuit
pattern generated by using a stored CP aperture for charged-particle beam exposure

and a circuit pattern generated by using the stored CP aperture and a CP aperture to be newly produced, and obtains a plurality of design parameters for each of the circuit patterns; and

the third instruction means presents said plurality of design parameters to the person who wishes to place an order for each of the circuit patterns and allows the person who wishes to place an order to select a circuit pattern satisfying a desired condition.

11. Canceled